

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



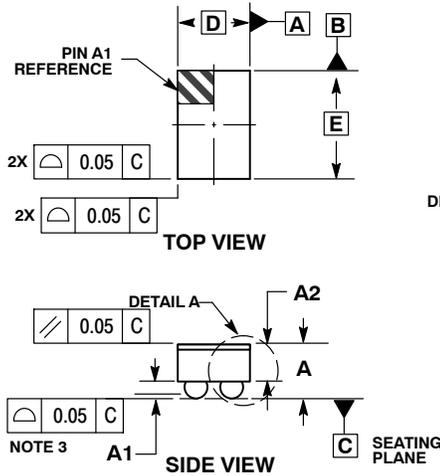
SCALE 4:1

### WLCSP6, 0.80x1.20

#### CASE 567FY

#### ISSUE B

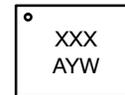
DATE 15 SEP 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

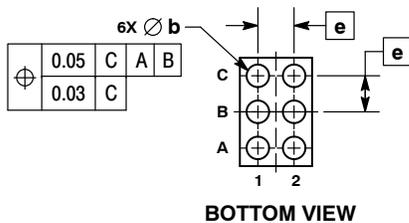
MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.28	REF
A3	0.04	REF
b	0.21	0.25
D	0.80	BSC
E	1.20	BSC
e	0.40	BSC

### GENERIC MARKING DIAGRAM\*

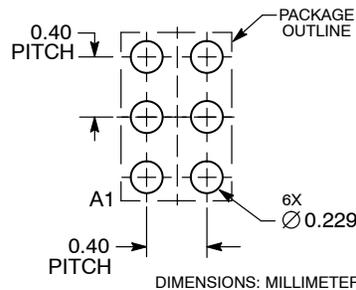


- A = Assembly Location
- Y = Year
- W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.



### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP6, 0.80X1.20</b>	<b>PAGE 1 OF 1</b>

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